Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/538509	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/04 09:10
S2	16	"4625075"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 14:30
S3	9	"4504700"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 14:33
S4	1244	345/174	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2008/02/02 14:33
S5	0	2001EP-1102331.ap,prai.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 15:15
S6	1	"1102331"	EPO	OR	ON	2008/02/02 15:17
S7	2	JP-01281622-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/02 15:20
S8	0	anolog same resistive same (touch near panel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/04 09:12
S9	210	analog same resistive same (touch near panel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:48
S10	4	"6812065"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/04 10:40

S11	5	("3624619" "4164622" "4208648").PN. OR ("4504700"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 09:36
S12	14	("3621268" "4198623" "4484179" "4504700" "4593191" "4609816" "4812833" "4837430" "5136156" "5266949" "5818037" "5887995").PN. OR ("6788295").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 09:37
S13	3	("20030067580" "5800175" "6965375").PN. OR ("7253808"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 09:42
S14	18	("3914021" "4432733" "5675397" "5760862" "5844175" "5888076" "5930663" "5990989" "6091474" "6191838" "6229695" "6506059" "6538709").PN. OR ("6965375"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 09:44
S15	161	analog same resistive and (touch near panel) and wire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 09:52
S16	7	("5854881" "6075520" "6124848").PN. OR ("6373474"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 09:54
S17	5	("20040251402" "5999279" "6043810" "6215477" "6370067").PN. OR ("7105752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 11:28
S18	0	2002/0101410	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:28
S19	3	"20020101410"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:28
S20	2	"7034808"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:47

S21	9723	345/173	US-PGPUB;	OR	ON	2008/02/05 11:47
	5.23		USPAT; EPO; JPO; DERWENT; IBM_TDB			
S22	1657167	wire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:47
S23	1583	S21 and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:47
S24	7293	analog same resistive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 11:48
S25	151	S23 and S24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 12:08
S26	352	(178/18.05).CCLS.	USPAT; USOCR	OR	OFF	2008/02/05 12:09
S27	172	wire with electrode with micrometer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 12:17
S28	13	wire with electrode with (micrometer micron) same display	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 12:18
S29	156	wire with electrode with (micrometer micron) and display	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 12:35
S30	40	"5,844,506"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 12:47

531	77	"100" near (micron micrometer) near electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 13:46
532	49	("100" "90" "80" "70" "60" "50" "40" "30") near (micron micrometer) near electrode and resist\$4 and display	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:24
S33	302	("100" "90" "80" "70" "60" "50" "40" "30") near (micron micrometer) near diameter with electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2008/02/05 13:55
S34	96	("100" "90" "80" "70" "60" "50" "40" "30") near (micron micrometer) near diameter with electrode with wire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 15:05
S35	. 823	electrode with wire with (conduct\$3 with paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 15:07
S36	3	S24 and S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 15:06
S37	11	S21 and S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 15:07
538	427	("100" "90" "80" "70" "60" "50" "40" "30" "95" "85" "75" "65" "55" "45" "35") near (micron micrometer "µm") near20 electrode and resist\$4 and (conductive with (paste adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:30
S39	5	("100" "90" "80" "70" "60" "50" "40" "30" "95" "85" "75" "65" "55" "45" "35") near (micron micrometer "µm") near20 electrode and resist\$4 and (conductive with (paste adhesive)) and (touch with panel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:40

	EAST Scarciff History							
S40	19	("100" "90" "80" "70" "60" "50" "40" "30" "95" "85" "75" "65" "55" "45" "35") near (micron micrometer "µm") near20 electrode and resist\$4 and (conductive with (paste adhesive)) and (touch with (panel screen surface pad))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:46		
S41	317398	("100" "90" "80" "70" "60" "50" "40" "30" "95" "85" "75" "65" "55" "45" "35") near (micron micrometer "µm") ((".03" ".04" ".05" ".06" ".07" ".08" ".09" ".1") near (millimeter "mm"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:54		
S42	7223	(S41 near10 (electrode wire))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:56		
543	186251	(conduct\$3 with (paste adhesive glue cement bond epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 17:02		
S44	180698	(touch with (panel screen surface pad))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:58		
S45	4269	S43 and S44	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:58		
S46	39	S42 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 16:58		
S47	179	S'42 and S44	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/05 17:03		

S48	21	("20020192441" "20030005955" "20030204038" "20040084080" "20040103936" "20040146560" "20040178390" "4865999" "4939050" "5571612" "6291763"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 17:16
		"6414235" "6444296" "6472594" "6515218" "6517958" "6586764" "6706962" "6852920").PN. OR ("6936761"). URPN.				
S49	10	("20020173354" "20030002273" "20040070335" "20040080267" "20040119403" "4683360" "4723080" "5450299" "5680160" "5947584").PN. OR ("7258469"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/05 17:20
S50	2024	wire with conductive with paste	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:51
S51	45504	("345").CLAS.	USPAT; USOCR	OR	OFF	2008/02/07 12:51
S52	10	S50 and S51	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 12:52
S53	3318	("100" "90" "80" "70" "60" "50" "40" "30" "95" "85" "75" "65" "55" "45" "35") near (micron micrometer "µm") near20 electrode and resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:06
S54	65	S51 and S53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:07
S55	14218	(micron micrometer "µm") near5 electrode and resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:22
S56	530	S51 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:23

S57	130790	touch near10 (screen pad panel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:23
S58	219	S55 and S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 13:24
S59	0	S51 near mm with (touch near panel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 14:11
S60	78	mm with (touch near panel) with (thin thick width)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 14:12
S61	15098	(("0.1" ".1") near (mm milimeter)(micron micrometer "µm")) near5 electrode and resist\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 14:30
S62	535	S51 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 14:31
S63	5	S62 not S56	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 14:32
S64	61	(("0.1" ".1") near (mm milimeter)(micron micrometer "µm")) near5 (electrode trace wire lead)and (resist\$4 with touch with (panel pad screen))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 14:45
S65	1152	((("0.1" ".1") near (mm milimeter))(micron micrometer "µm")) near5 ((electrode trace wire lead)with copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 16:11
S66	5	2001/0036504	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 16:35

S67	2	"20010036504"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/07 16:36
S68	130873	touch near10 (screen pad panel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:49
S69	148977	("100" "200") with micron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:50
S70	1292	S68 and S69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:50
S71	429128	ito	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:50
S72	237	S68 and S69 and S71	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:51
S73	4	extrode with external	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:58
S74	94936	electrode with external	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:58
S75	40	S68 and S69 and S74	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 12:58
S76	2606139	electrode connector	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 13:01

S77	842	S68 and S69 and S76	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 13:01
S78	3348	S69 with S76	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 13:03
S79	18	S68 and S78	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/12 13:03